PRELIMINARY

CY7C1199

32K x 8 Static RAM

Features

- **High speed**
  - **—15 ns t_{AA}**
- **Single 5V power supply with 3.3V-compatible I/Os**
  - **—V_{OH} max. of 3.435V**
- **Fast t_{DOE}**

Functional Description

The CY7C1199 is a high-performance CMOS static RAM organized as 32,768 words by 8 bits. The device operates with a single 5V power supply but internally clamps the output voltage level to a maximum of 3.435V. The internal clamps allow the CY7C1199 to interface to 3.3V processors (such as the Pentium™ processor) without buffers or level translators.

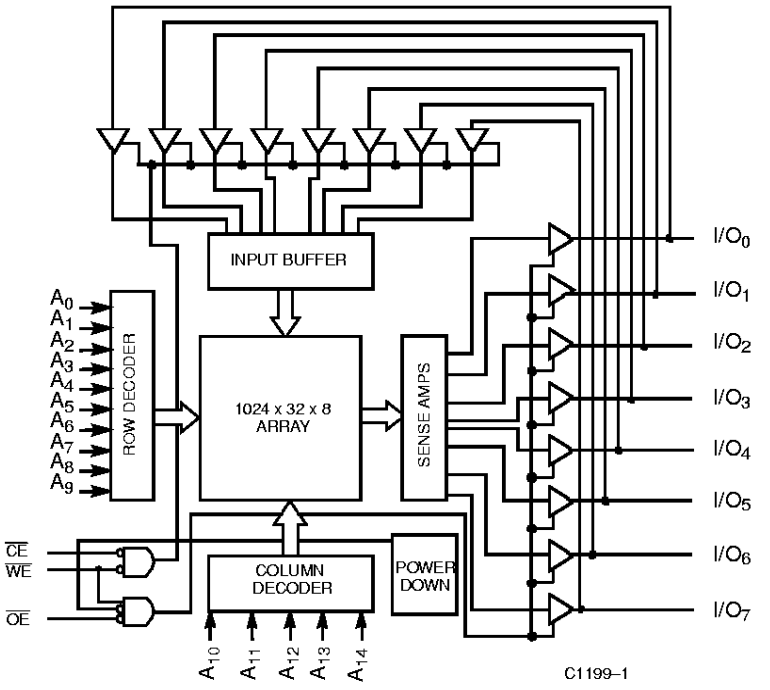
Easy memory expansion is provided by an active LOW chip enable ($\overline{CE}$) and active LOW output enable ($\overline{OE}$) and three-state drivers. This device has an automatic power-down feature, that reduces the power consumption significantly when deselected.

An active LOW write enable signal ($\overline{WE}$) controls the writing/reading operation of the memory. When $\overline{CE}$ and $\overline{WE}$ inputs are both LOW, data on the eight data input/output pins (I/O_0 through I/O_7) is written into the memory location addressed by the address present on the address pins (A_0 through A_{14}). Reading the device is accomplished by selecting the device and enabling the outputs, $\overline{CE}$ and $\overline{OE}$ active LOW, while $\overline{WE}$ remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable ($\overline{WE}$) is HIGH.

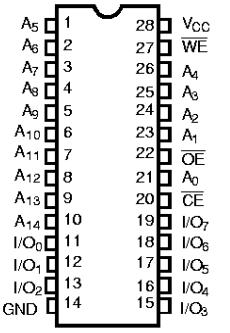
The CY7C1199 is available in standard 300-mil-wide SOJ packages.

Logic Block Diagram



Pin Configurations

SOJ
Top View



C1199–2

Selection Guide

		7C1199–15	7C1199–20
Maximum Access Time (ns)		15	20
Maximum Operating Current (mA)	Com'l	130	125
Maximum Standby Current (mA)	Com'l	30	30

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Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... –65°C to +150°C

Ambient Temperature with Power Applied ..... –55°C to +125°C

Supply Voltage to Ground Potential (Pin 28 to Pin 14) ..... –0.5V to +7.0V

DC Voltage Applied to Outputs in High Z State[1] ..... –0.5V to V_{CC} + 0.5V

DC Input Voltage[1] ..... –0.5V to V_{CC} + 0.5V

Output Current into Outputs (LOW) ..... 20 mA

Static Discharge Voltage ..... >2001V (per MIL-STD-883, Method 3015)

Latch-Up Current ..... >200 mA

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to +70°C	5V ± 10%

Electrical Characteristics Over the Operating Range[2]

Parameter	Description	Test Conditions		7C1199–15		7C1199–20		Unit
				Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	–100 µA ≤ I_{OH} ≤ –4.0 mA		2.4	3.435	2.4	3.435	V
V_{OL}	Output LOW Voltage	I_{OL} = 8.0 mA			0.4		0.4	V
V_{IH}	Input HIGH Voltage			2.2	V_{CC} +0.3V	2.2	V_{CC} +0.3V	V
V_{IL}	Input LOW Voltage			–0.5	0.8	–0.5	0.8	V
I_{IX}	Input Load Current	GND ≤ V_I ≤ V_{CC}		–5	+5	–5	+5	µA
I_{OZ}	Output Leakage Current	GND ≤ V_O ≤ V_{CC}, Output Disabled		–5	+5	–5	+5	µA
I_{OS}	Output Short Circuit Current[3]	V_{CC} = Max., V_{OUT} = GND			–300		–300	mA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = 1/t_{RC}	Com'l		130		125	mA
I_{SB1}	Automatic CE Power-Down Current— TTL Inputs	Max. V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}	Com'l		30		30	mA
I_{SB2}	Automatic CE Power-Down Current— CMOS Inputs	Max. V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3V V_{IN} ≥ V_{CC} – 0.3V or V_{IN} ≤ 0.3V, f = 0	Com'l		10		10	mA

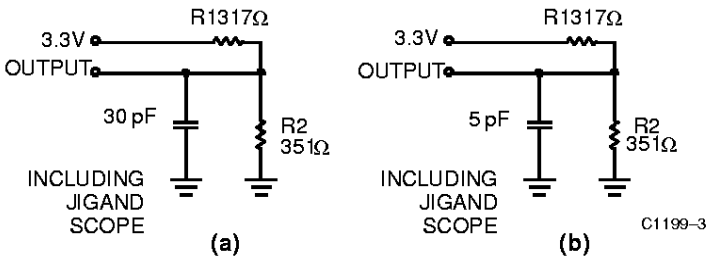
Capacitance[4]

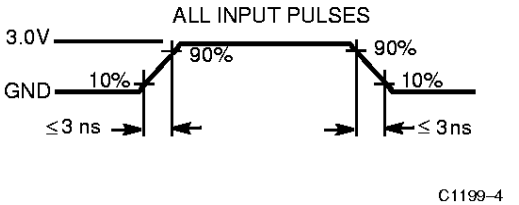
Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	T_A = 25°C, f = 1 MHz, V_{CC} = 5.0V	8	pF
C_{OUT}	Output Capacitance		8	pF

Notes:

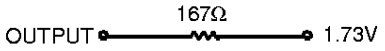
1. V_{IL} (min.) = –2.0V for pulse durations of less than 20 ns.
2. See the last page of this specification for Group A subgroup testing information.
3. Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
4. Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms[5]





Equivalent to: THÉVENIN EQUIVALENT



Switching Characteristics Over the Operating Range[2, 5]

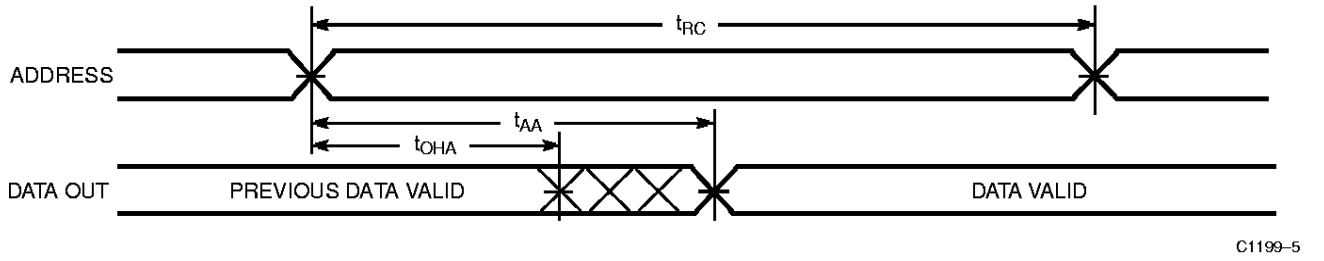
Parameter	Description	7C1199–15		7C1199–20		Unit
		Min.	Max.	Min.	Max.	
READ CYCLE						
t_{RC}	Read Cycle Time	15		20		ns
t_{AA}	Address to Data Valid		15		20	ns
t_{OHA}	Data Hold from Address Change	3		3		ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid		15		20	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid		5		6	ns
t_{LZOE}	$\overline{OE}$ LOW to Low Z[6]	0		0		ns
t_{HZOE}	$\overline{OE}$ HIGH to High Z[6, 7]		7		9	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z[6]	3		3		ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z[6, 7]		7		9	ns
t_{PU}	$\overline{CE}$ LOW to Power-Up	0		0		ns
t_{PD}	$\overline{CE}$ HIGH to Power-Down		15		20	ns
WRITE CYCLE[8, 9]						
t_{WC}	Write Cycle Time	15		20		ns
t_{SCE}	$\overline{CE}$ LOW to Write End	10		15		ns
t_{AW}	Address Set-Up to Write End	10		15		ns
t_{HA}	Address Hold from Write End	0		0		ns
t_{SA}	Address Set-Up to Write Start	0		0		ns
t_{PWE}	$\overline{WE}$ Pulse Width	9		15		ns
t_{SD}	Data Set-Up to Write End	8		9		ns
t_{HD}	Data Hold from Write End	0		0		ns
t_{HZWE}	$\overline{WE}$ LOW to High Z[7]		7		10	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low Z[6]	3		3		ns

Notes:

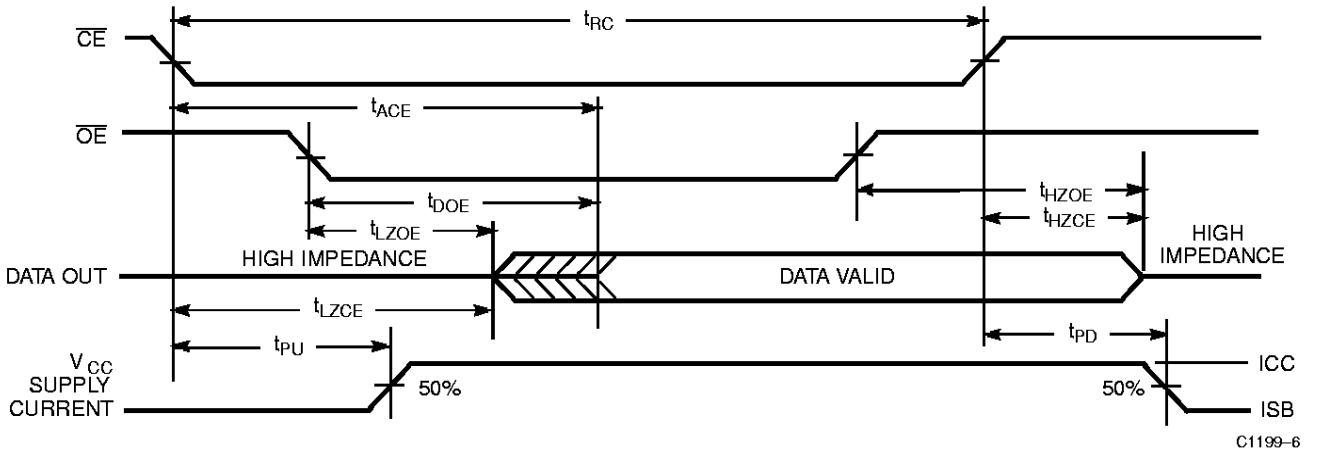
5. Test conditions assume timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
6. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
7. t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with C_L = 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
8. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
9. The minimum write cycle time for write cycle #3 ($\overline{WE}$ controlled, $\overline{OE}$ LOW) is the sum of t_{HZWE} and t_{SD}.

Switching Waveforms

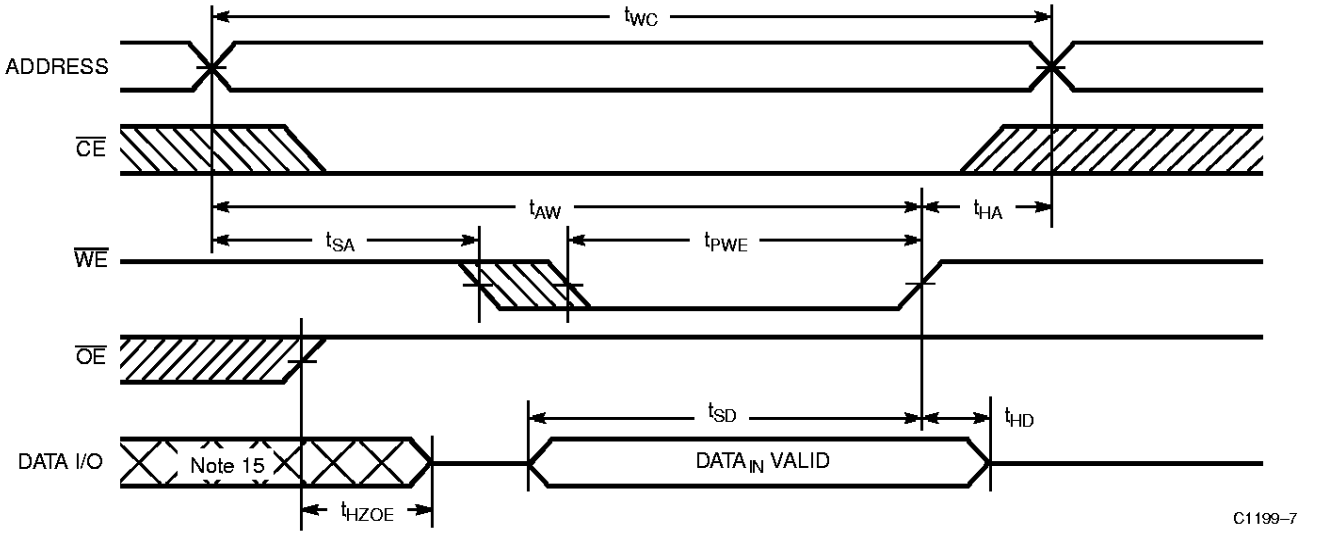
Read Cycle No. 1[10, 11]



Read Cycle No. 2[11, 12]



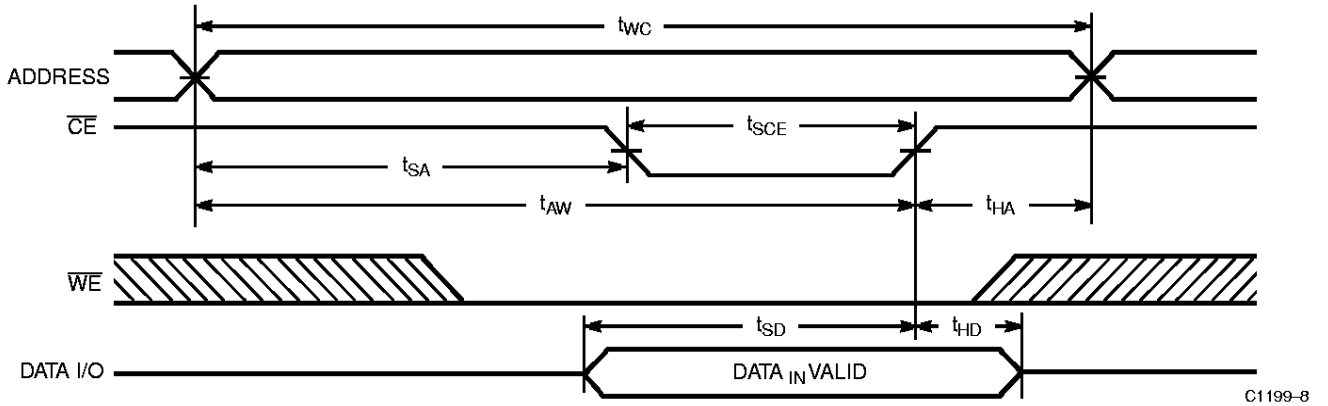
Write Cycle No. 1 ($\overline{WE}$ Controlled)[8, 13, 14]



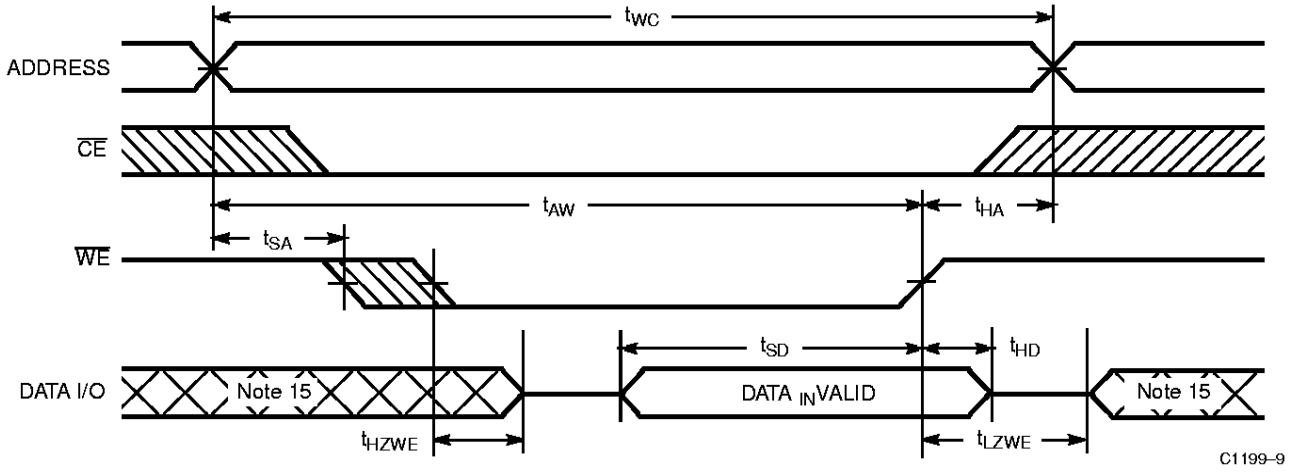
Switching Waveforms (continued)

Notes:
10. Device is continuously selected. $\overline{OE}$, $\overline{CE}$ = V_{IL}.
11. $\overline{WE}$ is HIGH for read cycle.
12. Address valid prior to or coincident with $\overline{CE}$ transition LOW.
13. Data I/O is high impedance if $\overline{OE}$ = V_{IH}.
14. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ HIGH, the output remains in a high-impedance state.
15. During this period, the I/Os are in the output state and input signals should not be applied.

Write Cycle No. 2 ($\overline{CE}$ Controlled)[8, 13, 14]

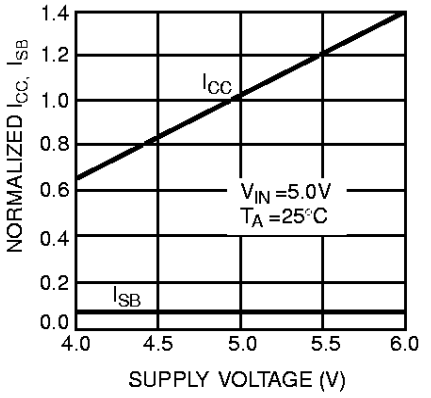


Write Cycle No. 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)[9, 14]

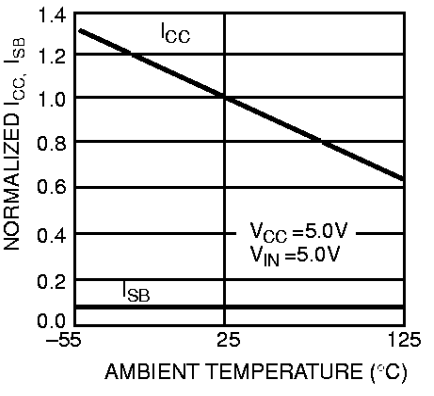


Typical DC and AC Characteristics

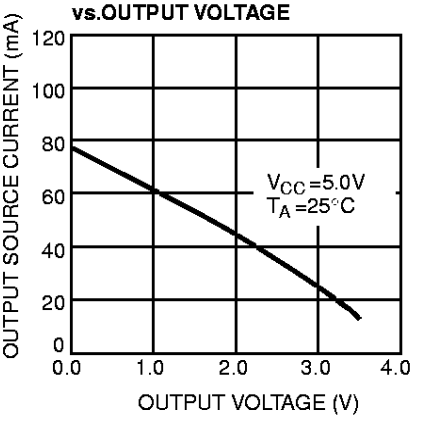
NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



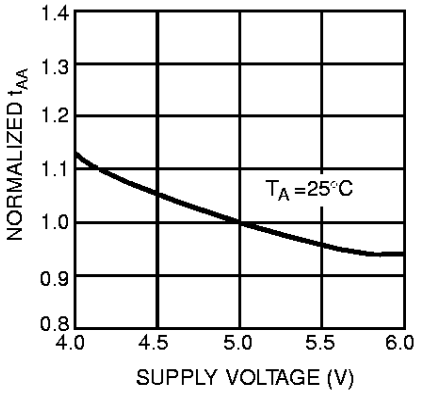
NORMALIZED SUPPLY CURRENT vs. AMBIENT TEMPERATURE



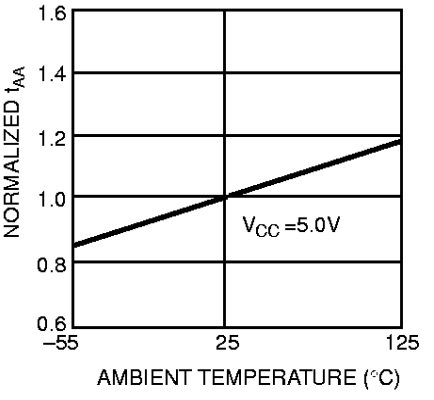
OUTPUT SOURCE CURRENT vs.OUTPUT VOLTAGE



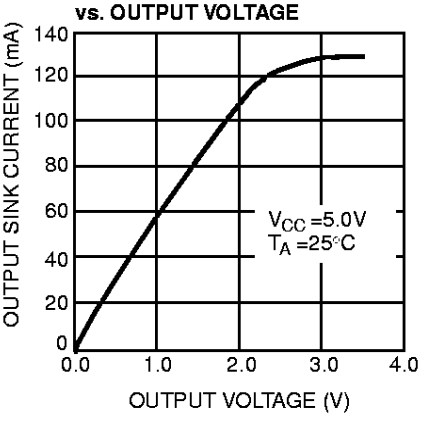
NORMALIZED ACCESS TIME vs. SUPPLY VOLTAGE



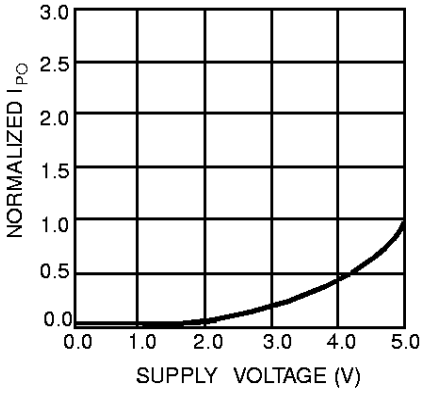
NORMALIZED ACCESS TIME vs. AMBIENT TEMPERATURE



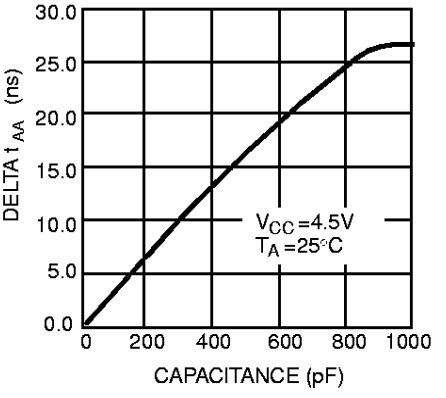
OUTPUT SINK CURRENT vs. OUTPUT VOLTAGE



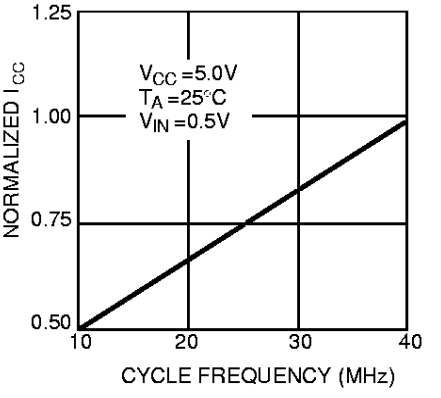
TYPICAL POWER–ON CURRENT vs. SUPPLY VOLTAGE



TYPICAL ACCESSTIME CHANGE vs. OUTPUT LOADING



NORMALIZED I_{CC} vs. CYCLE TIME



Truth Table

$\overline{CE}$	$\overline{WE}$	$\overline{OE}$	Inputs/Outputs	Mode	Power
H	X	X	High Z	Deselect/Power-Down	Standby (I_{SB})
L	H	L	Data Out	Read	Active (I_{CC})
L	L	X	Data In	Write	Active (I_{CC})
L	H	H	High Z	Deselect, Output Disabled	Active (I_{CC})

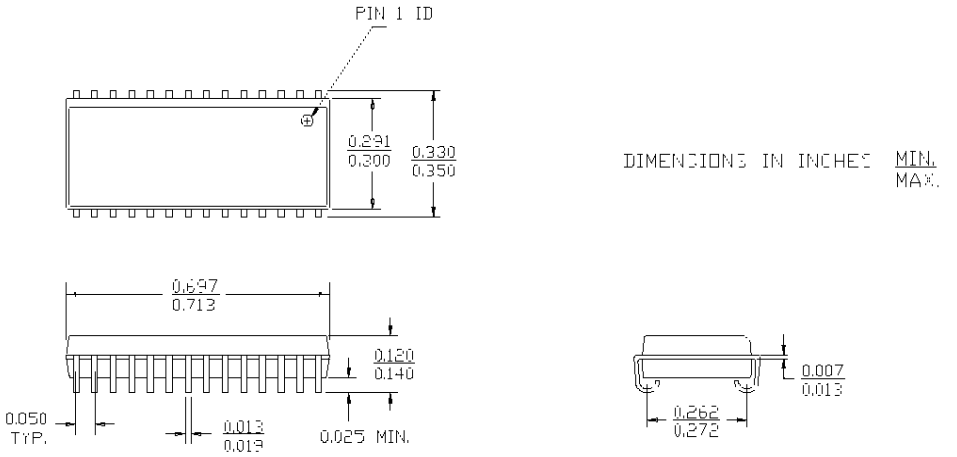
Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
15	CY7C1199–15VC	V21	28-Lead Molded SOJ	Commercial
20	CY7C1199–20VC	V21	28-Lead Molded SOJ	Commercial

Document #: 38–00460

Package Diagram

28-Lead (300-Mil) Molded SOJ V21



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